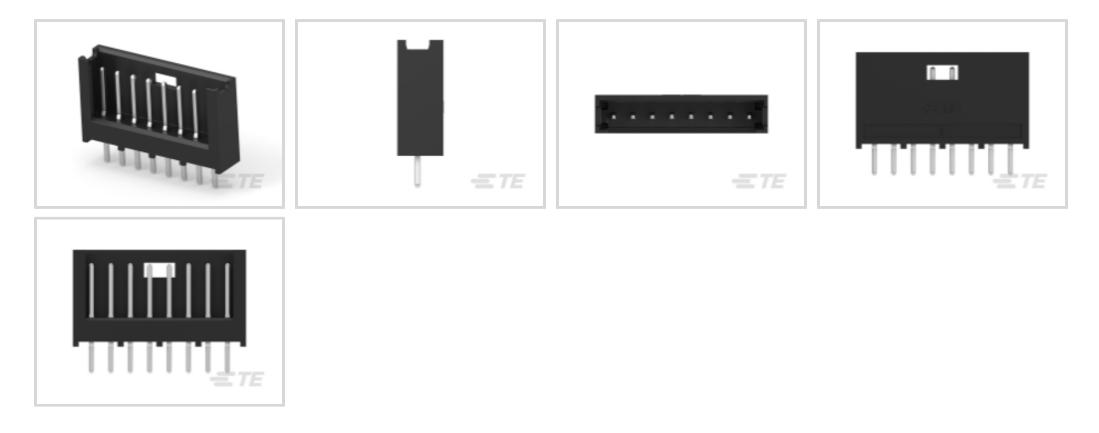
280373-1 🗸 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 280373-1 PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [. 1 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, AMPMODU Headers

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 8

Number of Rows: 1

Features

E

Product Type Features

Connector Shape	Rectangular				
PCB Connector Assembly Type	PCB Mount Header				
Connector System	Board-to-Board				
Header Type	Partially Shrouded				
Sealable	No				
Connector & Contact Terminates To	Printed Circuit Board				
Configuration Features					
Connector Contact Load Condition	Fully Loaded				
Connector Contact Load Condition PCB Mount Orientation	Fully Loaded Vertical				
PCB Mount Orientation	Vertical				
PCB Mount Orientation Number of Positions	Vertical				
PCB Mount OrientationNumber of PositionsNumber of Rows	Vertical				

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Body Features

Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Contact Mating Area Length	6.6 mm[.259 in]
Mating Square Post Dimension	.63 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	3 – 5 µm[118.11 – 196.85 µin]
Contact Layout	Inline
Contact Underplating Material Thickness	1.27 μm[50 μin]
Contact Shape & Form	Square
Contact Mating Area Plating Material Finish	Bright
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Brass
Contact Mating Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	3 – 5 μm[118.11 – 196.85 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A

Termination Features

Termination Post & Tail Length	3.5 mm[.138 in]		
Termination Method to PCB	Through Hole - Solder		
Mechanical Attachment			
Mating Retention	With		
Panel Mount Feature	Without		
Mating Alignment	With		
Mating Alignment Type	Polarization		
PCB Mount Retention	Without		
PCB Mount Alignment	Without		
Connector Mounting Type	Board Mount		
Housing Features			
Centerline (Pitch)	2.54 mm[.1 in]		
Housing Material	Flame Retardant Thermoplastic		

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Dimensions

Connector Length	22.9 mm[.901 in]					
Connector Height	12.6 mm[.496 in]					
Connector Width	5 mm[.197 in]					
Row-to-Row Spacing	2.54 mm[.1 in]					
Usage Conditions						
Housing Temperature Rating	Standard					
Operating Temperature Range	-40 – 80 °C[-40 – 176 °F]					
Operation/Application						
Circuit Application	Power & Signal					
Industry Standards						
Industry Standard	IEC					
UL Flammability Rating	UL 94V-0					
Packaging Features						
Packaging Quantity	500					
Packaging Method	Box					

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, AMPMODU Headers



will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Also in the Series AMPMODU Headers

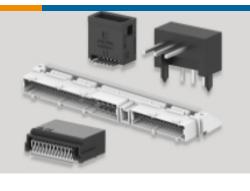




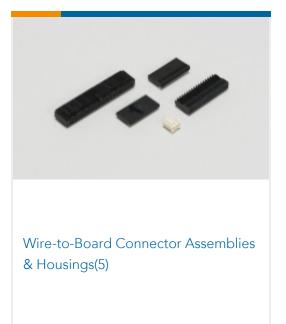
Connector Contacts(64)



Connector Hardware(2)



PCB Headers & Receptacles(3202)



Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 8 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Tin, Through Hole - Solder, AMPMODU Headers







Documents

Product Drawings 8P AMPMODU II SHRD HDR, ST, TIN

English

CAD Files 3D PDF

3D

Customer View Model ENG_CVM_CVM_280373-1_U_c-280373-1-u.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_280373-1_U_c-280373-1-u.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_280373-1_U_c-280373-1-u.3d_stp.zip

English

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